

Technical Characteristics

3U/6U form factor	P1/P4	P2/P5	P3	J1/J4	J2/J5	J3
Part Number	K2A110FMD	K2B110FMD	K2B095FMD	K2A110FFD	K2B110FFD	K2B095FFD
Design Criteria	IEC 1076-4 101					
Quality Conformance Inspections	K2 Series: MIL-DTL-55302		311P Series: NASA GSFC S-311-P-822 ⁽¹⁾			
Contact Gender	Male Pin			Female Socket		
Contact Spacing	0.079 [2.00]					
Number of Contacts	110 signal, 22 ground		95 signal, 19 ground	110 signal, 22 ground		95 signal, 19 ground
Max. Allowable Gap <i>(Between Mating Connectors)</i>	0.039 [1.00]					
Suggested PCB Hole Diameter	0.028 [0.71] ± 0.002 [0.05] after plating			0.023 [0.60] after plating		

Materials

Contact Termination	Sold tail: 63/37 tin lead plated	Gold or 63/37 tin lead dipped
Insulation	30% glass filled LCP <i>(meets NASA outgassing specification)</i>	
Contact	Beryllium copper	Beryllium copper socket wires, brass body
Mating Contact	50 µin gold/50 µin nickel min.	

Mechanical & Environmental

Temperature Range	-55 to 125° C					
Flammability Range	94 V-O					
Weight	0.55 oz.	0.53 oz.	0.38 oz.	0.38 oz.	0.45 oz.	0.31 oz.
Mating Force	16.38/13.20 LBF average per mating connect pair					
Contact Life Cycle	> 4,000 per mated connector pair					
Vibration <i>(Sinusoidal)</i>	Frequency 10 to 2,000 HZ at 15 G (MIL-DTL-55302)(NASA GSFC S311-P-822)					
Vibration <i>(Random)</i>	Fight chassis unit level vibration (NASA Goddard SE Rev 1)					
Mechanical Shock	100 G peak value (NASA GSFC S311-8220)					

Electrical

Insulation Resistance	> 5,000 megohms					
CRD <i>(Resistance at Rated Current)</i>	4.85 milliohms average					
LLCR <i>(Low Level Contact Resistance)</i>	7.20 milliohms average					
DWV <i>(Dielectric Withstanding Voltage)</i>	1,000 V RMS					

1) K2 Series: Standard cPCI; 311P Series: NASA Goddard cPCI

Dimensions are in inches [mm]